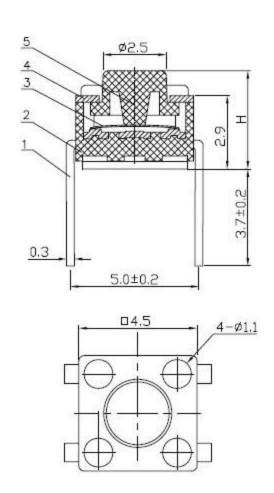
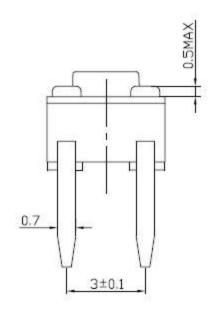
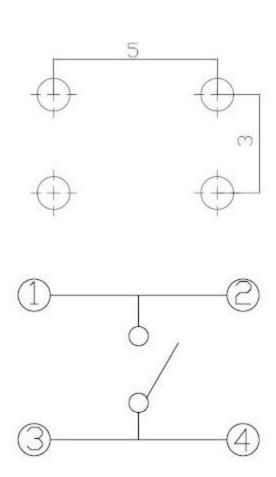


APPROVAL SPECIFICATIONS







-20°Cto+70°C
50mA.12V DC
100M Ω min.100V DC
250V AC for 1 min
100MΩ max
0.25±0.1mm
3.8/4.3/4.5/5/5.5/6/7mm
100gf/160gf/260gf

Conditions for Auto-dlp		
Items	Condition	
Flux built-up	Mounting surface should not be coated with flax	
Preheating temperature	印刷电路板焊接面的周围温度100°C max Ambient temperature of the soldered surface of PC board. 100°C max.	
Preheating time	60s max.	
Soldering temperature	260°C max.	
Continuous dipping time Number of soldering	5s max.焊接次数 2次以下/ 2times max.	

Hand soldering

请按以下条件进行焊接: (1) 焊锡温度: ≤350℃ (2) 连续焊接时间: ≤3 s

Please practice according to below conditions: (1) Soldering temperature: 350°C Max. (2) Continuous soldering time: 3 s Max.